

Specification Sheet

Cu, PPI-50PPI, Thickness; 2mm

Stock No: NS6130-10-1007, CAS: 7440-50-8

Product	:	Metallic Copper Foamposite
Stock No	:	NS6130-10-1007
CAS	:	7440-50-8
Porosity	:	>70%
Dimension	:	500mm X 500mm
Thickness	:	2mm
PPI	:	50
Molecular Formula	:	Cu
Molecular weight	:	63.55g/mol
Density	:	8.96g/cm ³
Melting point	:	1085°C
Boiling point	:	2562°C
Thermal expansion	:	16.5µm.m ⁻¹ .k ⁻¹
Thermal conductivity	:	401W.m ⁻¹ .k ⁻¹
Tensile strength	:	1.25N/mm
Young's modulus	:	110-128GPa
Shear strength	:	190Psi
Vickers hardness	:	369MPa
Poisson's ratio	:	0.34
Electrical resistivity	:	1.673µΩ-cm
Specific heat	:	0.39kj/kgK
Electronegativity	:	1.90paulings
Heat of fusion	:	13.26kJ.mol ⁻¹
Heat of vaporization	:	300.4kJ.mol ⁻¹
Main Inspect Verifier	:	Manager QC

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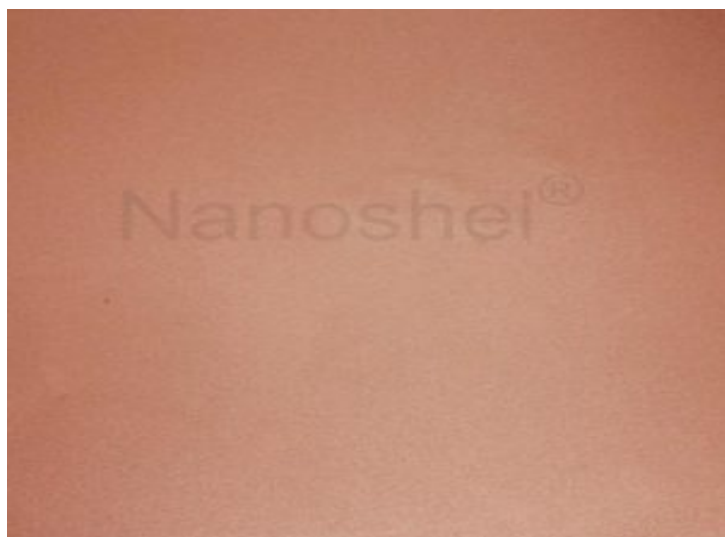


Note: Product Specification are subject to amendment and may change over time



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Characterization of Cu, PPI-50PPI, Thickness; 2mm



Metallic Copper Foamposite



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